Celanese
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HOSTAFORM® S 27063

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Chemical abbreviation according to ISO 1043-1: POM-HI, Molding compound ISO 29988- POM-K, M-GNPR, 05-001 POM copolymer, modified Easy flowing, medium impact modified injection molding type with higher impact strength and slightly lower hardness, rigidity and chemical resistance than unmodified acetal copolymer; high resistance to thermal and oxidative degradation. UL-registration in natural and a thickness more than 1.57 mm as UL 94 HB. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm thickness. Ranges of applications: For thin-walled molded parts with higher energy-absorbing capacity UL = Underwriters Laboratories (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM-HI	ISO 1043
Part Marking Code	>POM-HI<	ISO 11469

Rheological properties

Melt volume-flow rate	21	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	1950	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	51	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	30	%	ISO 527-1/-2
Flexural modulus	2100	MPa	ISO 178
Tensile creep modulus, 1h	1850	MPa	ISO 899-1
Tensile creep modulus, 1000h	1050	MPa	ISO 899-1
Charpy impact strength, 23°C	140	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	90	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	9	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	6	kJ/m^2	ISO 179/1eA
Puncture energy, 23°C	8	J	ISO 6603-2
Ball indentation hardness, H 358/30	115	MPa	ISO 2039-1
Poisson's ratio	0.443		

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	84	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2

Flammability

Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	1.6	mm	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	3.17	mm	IEC 60695-11-10
UL recognition	yes		UL 94

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Electrical properties

Relative permittivity, 100Hz	4.2		IEC 62631-2-1
Relative permittivity, 1MHz	4.2		IEC 62631-2-1
Dissipation factor, 100Hz	50	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	150	E-4	IEC 62631-2-1
Volume resistivity	1E11	Ohm.m	IEC 62631-3-1
Surface resistivity	1E13	Ohm	IEC 62631-3-2
Electric strength	28	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1390	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	195	°C
Min. melt temperature	190	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C
Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	High Flow

Additional information

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

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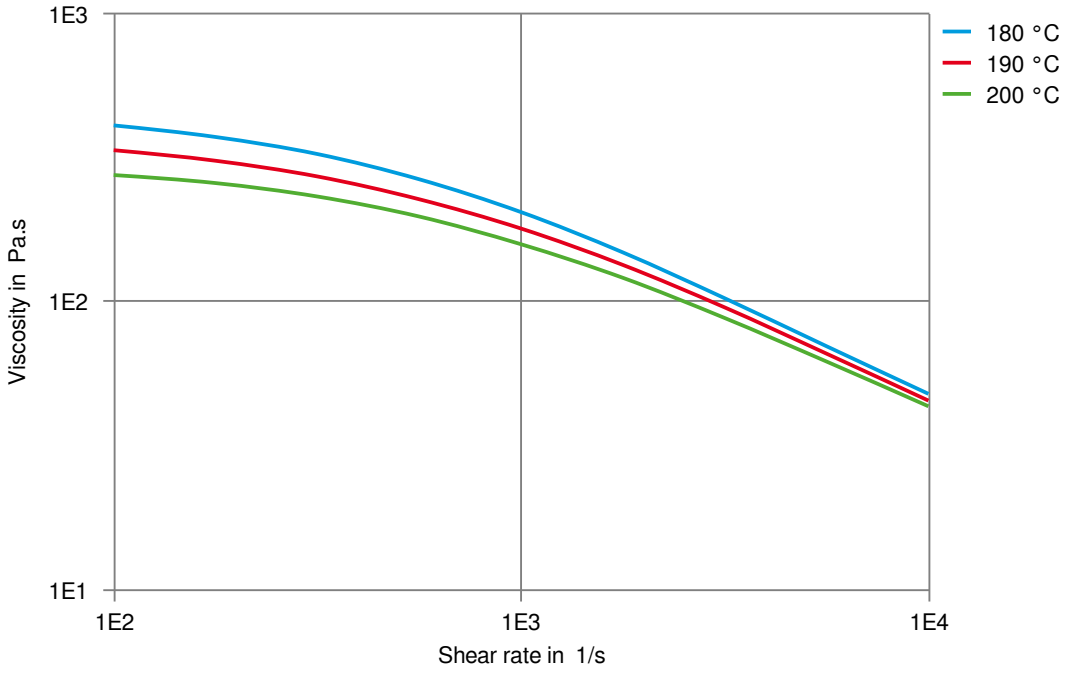
Automotive

OEM	STANDARD
BMW	GS93016

Viscosity-shear rate



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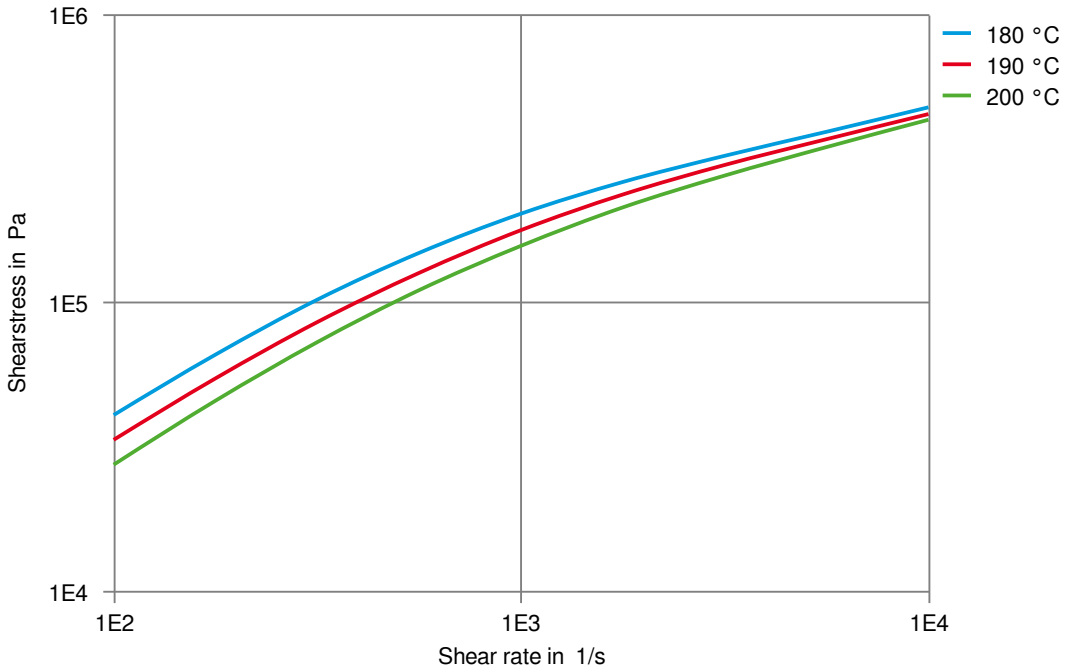
Shearstress-shear rate



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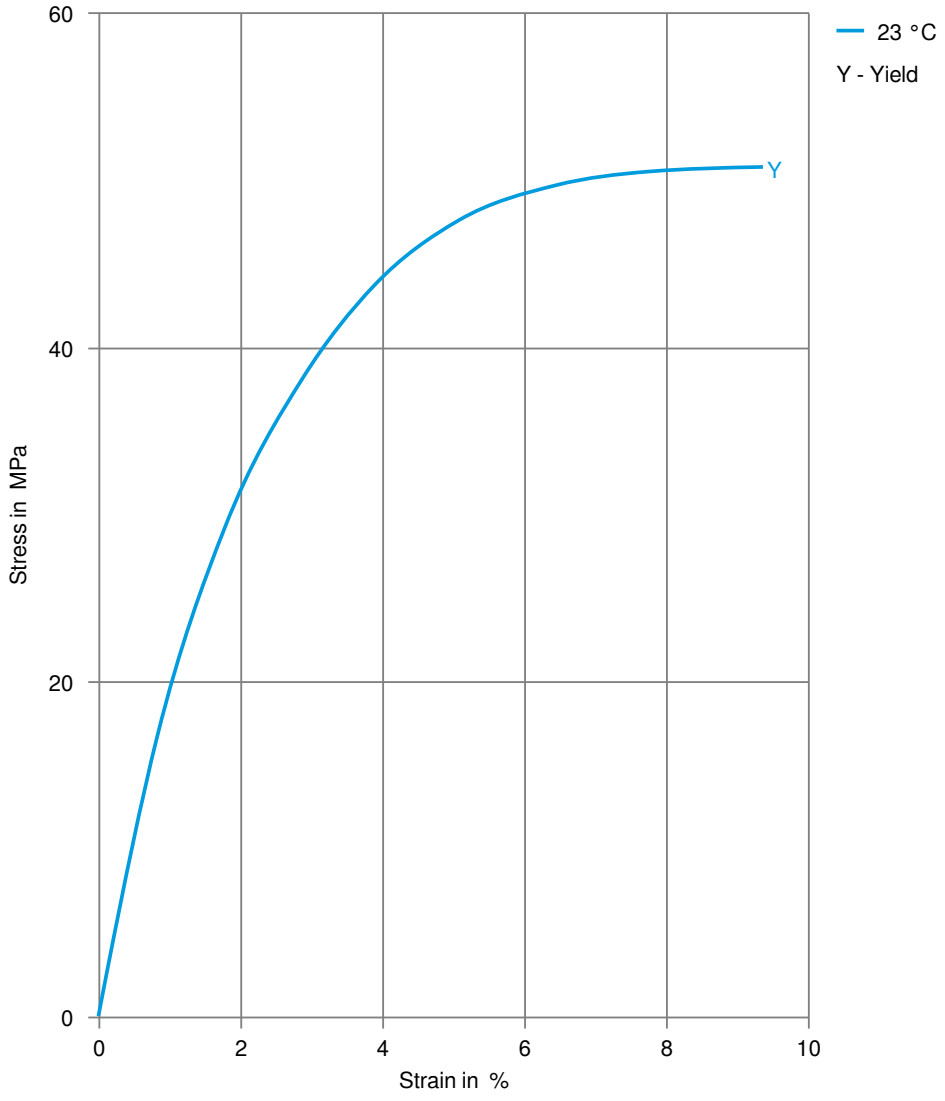
Stress-strain



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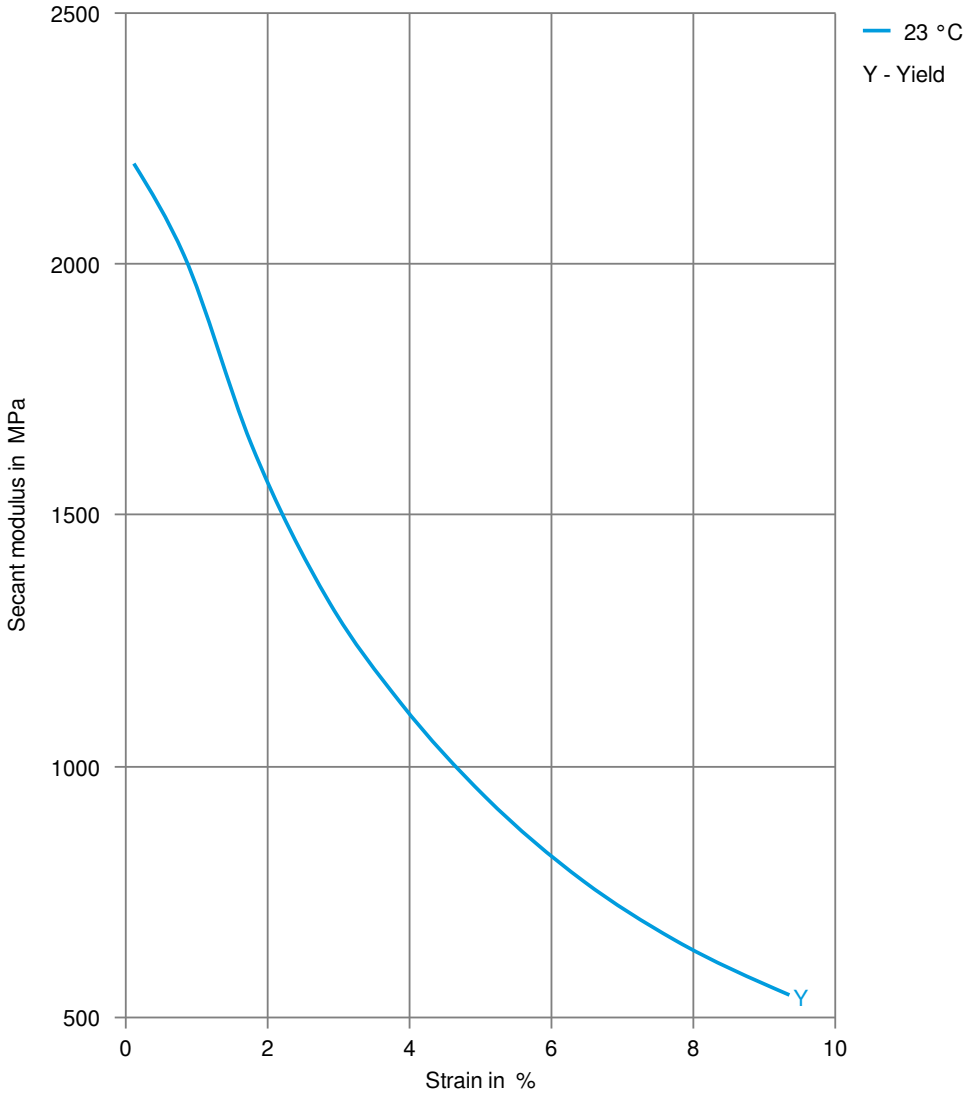
Secant modulus-strain



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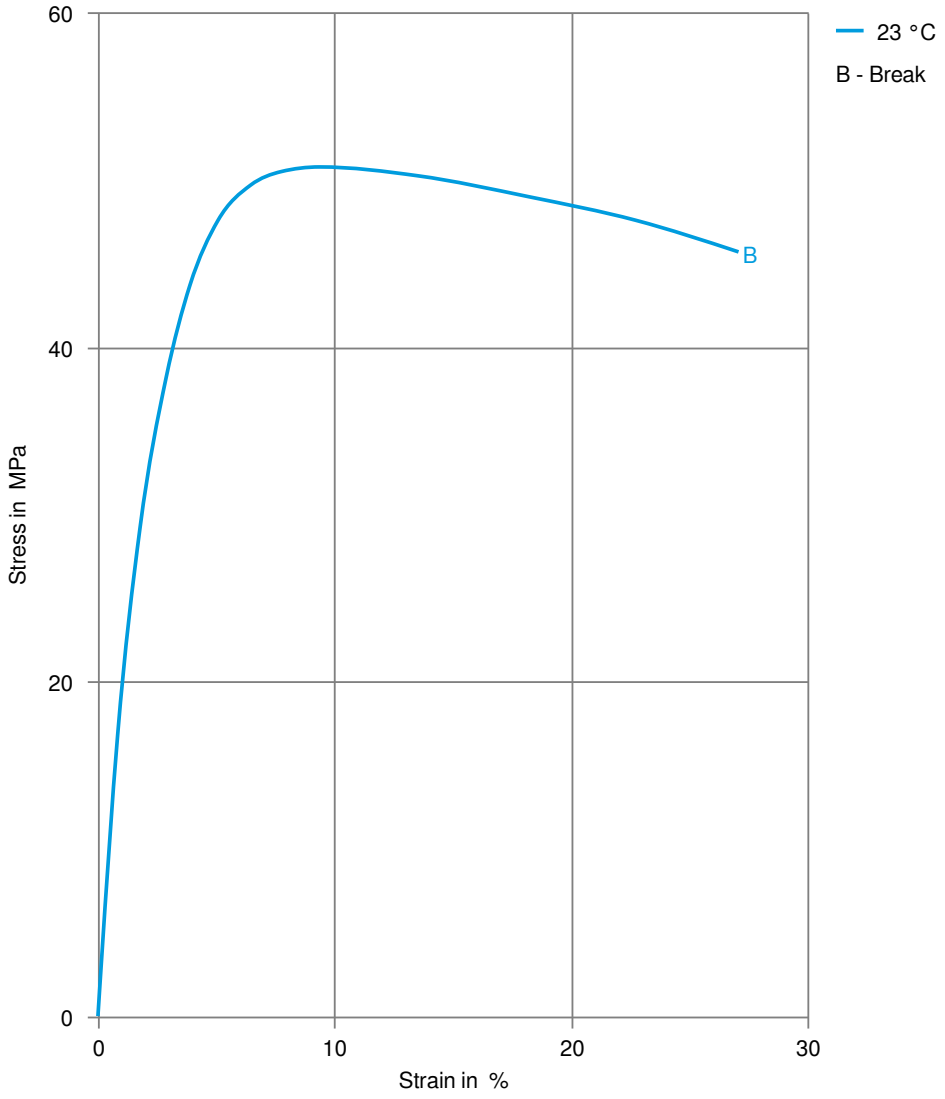
Stress-strain, 50mm/min



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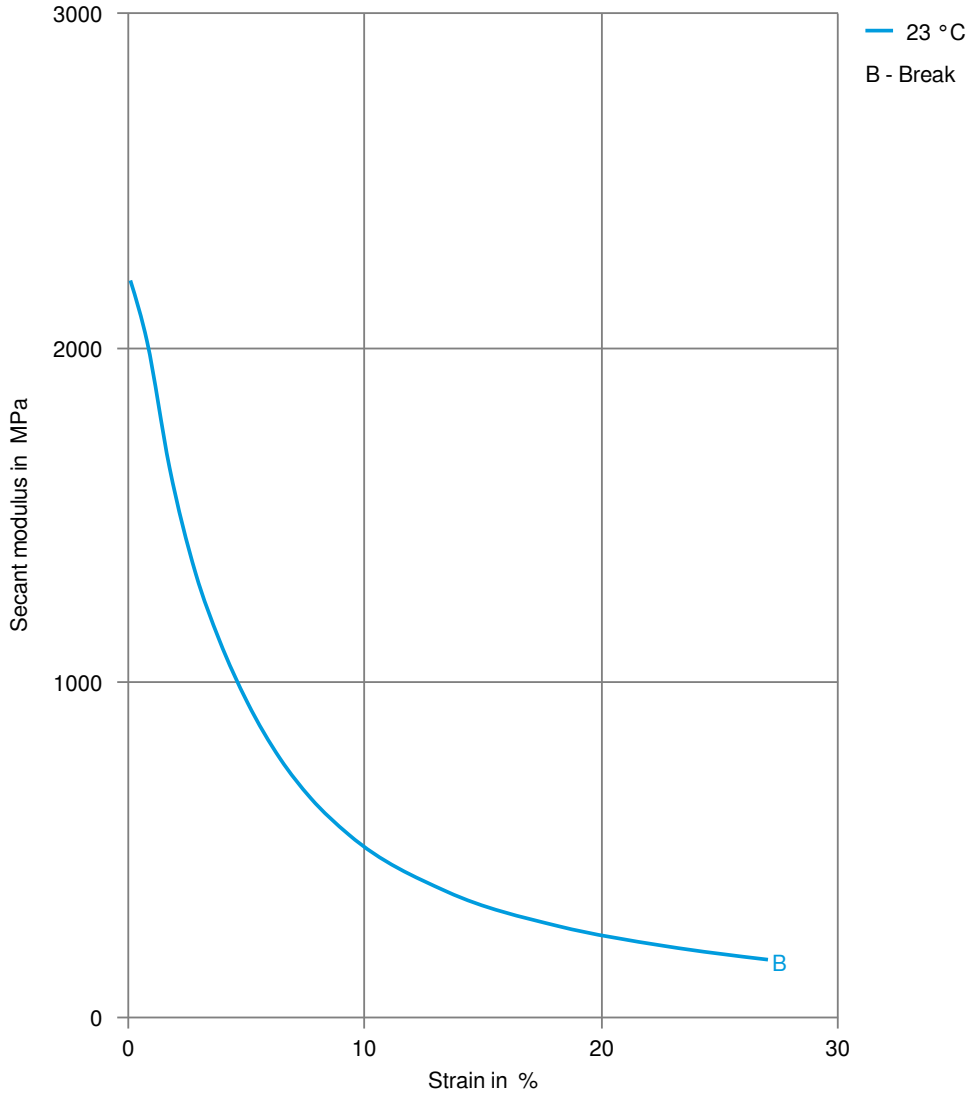
Secant modulus-strain, 50mm/min



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